



Main Features

- 11th Generation Intel® Core™ I Processors
- 1 x VGA and 1 x HDMI Display ports
- 2 x SO-DIMM DDR4 with non-ECC 2666MHz up to 64GB
- 2 x Intel® GbELAN ports and 1 x 2.5 GbELAN
- 7 x USB 3.2 (Gen1), 4 x USB 2.0
- 2 x RS232 and 2 x RS232/422/485
- 1 x SATA 3.0 port
- 1 x Full size Mini PCIe slot
- 2 x M.2 Key B
- Onboard TPM
- Support 0~60 °C extended operating temperature
- 24V DC input

Product Overview

RCB600 is equipped with Tiger Lake-UP3 11th generation Intel® Core™ I processor, with high-performance AI computing capabilities, high-performance architecture x86-64 for ROS development and visual recognition applications.

The I/O of various devices can be connected to various devices. Supports real-time I/O for environmental sensors (CAN, GPIO, COM).

Instant messaging software communicates between software components and devices.

RCB600 has rich IO interfaces, which can easily meet the diversified needs of robots, instead of being limited to simple handling robots. AMR is suitable for application services in different fields of various industrial enterprises, various manufacturing industries, building parks, medical institutions, e-commerce logistics related industrial services.

The introduction of AMR can not only greatly improve work efficiency and reduce the fixed cost of operating personnel!

It also conforms to current affairs applications such as "assisted labor-saving handling", "human-machine collaborative operation", "AMR/AGV", "IoT Internet of Things concept" and "epidemic".

Specifications

CPU Support

- 11th Generation Intel® Core™ I Processors Intel® 11th Generation Core™ i7/i5/i3 SoC.

Main Memory

- DDR4-3200 SO-DIMM sockets supported Dual Channel, Max. 64GB.

Display Option

- 1 x VGA (resolution up to 1920x1080@60Hz).
- 1 x HDMI 1.4b (resolution up to 4096x2304@60Hz)
- Tip: Multiple display : (VGA+HDMI).

System

- 7 x USB 3.2 (Gen1), 4 x USB 2.0.
- 2 x RS232, 2 x RS232/485/422, 1 x CAN bus.
- Realtek HDA Codec.
- 1 x Front panel header, 16 bit digital I/O (8In/8Out), 2 x DI/DO
- WDT, SMBus, Onboard TPM.
- 1 x Fan connector.

Storage

- 1 x SATA 3.0, 1 x SATA power connector (+5V).
- 1 x M.2 2242/2280 B-key (support SATA/PCIe/USB2.0).

Expansion Slot

- 1 x Full size mPCIe x 1 with Nano-SIM (support PCIe/USB2.0 Interface).
- 1 x M.2 3052/3042 key B (for LTE 5G), (USB3.2 (Gen1)/PCIe) with Nano-SIM.

Rear I/O

- 6 x USB 3.2 (Gen1).
- 1 x VGA, 1 x HDMI 1.4b.
- 2 x DB9 (by COM 1,2).
- 3 x GbE LAN
 - > LAN1 : Intel® I219-LM
 - > LAN2 : Intel® I225AT
 - > LAN3 : I210AT (Support EtherCAT)
- 1 x 2 ports HD Audio Jack (Mic-in, Line-out).

Block Diagram

The diagram illustrates the TGL-UP3 module's architecture and its various interfaces. The central processor, TGL-UP3 (28W, 4C/6T, 45.5 x 25 mm, 1449 BALLS), is the core component. It is connected to two DDR4 SO-DIMM modules (NON-ECC, 3200 MHz) via DDR4 CHA and CHB channels. The module features a variety of peripheral interfaces: LAN1~LAN3 (RJ45 Connector), Mini PCIe Slot, M.2 (B Key) Slot, M.2 (B Key) Slot, SATA CONN, and USB 3.2 GEN1 USB x6. A SIM CARD is also connected. On the right, it connects to HDMI 1 (Z97GT/s), VGA (CH7517), SSI (ICMB4), AUDIO (ALC888), SPI ROM, and TPM (SLB9670VQ2.0). At the bottom, it connects to an EC (IT5782) which manages DI / DO X2, CAN, XR34350, TRS213, COM1/COM2, RS232 COM3/COM4, and GPIO. A 80 Port connector is also shown. The diagram includes various signal lines like I2C, SPI, UART, and USB.

- 2 x USB2.0 (Pin Header).
- 4 x serial ports:
 - > 2 x RS232 (by COM 3,4)
 - > 2 x RS232/485/422 (by COM1,2)
- 1 x CANBus (WIRE to BD 1x2 KINGMATE:2001J-02-ST(GF))
- 1 x Front panel header, 1 x 16 bit digital I/O(8In/8Out),
2 x DI/ DO, WDT, SM bus.
- HA Audio:
 - > 1 x Speaker out, 1 x Line-Out, 1 x MIC-In
- 1 x 4Pin DC In (+24V).

- 1 x 4-pin (2x2) ATX Power connector.
 - Input power DC 12V or 24V Only (Auto Detect).
- Support both AT and ATX power supply mode.

- 6.7"x6.7" (170mm x 170 mm).

- Board level operation temperature: 0°C to 60°C
- Storage temperature: -40°C to 85°C
- Relative humidity:
 - 10% to 95% (operating, non-condensing)
 - 5% to 95% (non-operating, non-condensing)

- CE/FCC Class A & **IEC 61326-3-1.**

- Windows 10 (64bit).
- Ubuntu 18.04.05/Kernel 5.4

- **RCB600 (P/N: 10J200RCB08X0)**
Mini-ITX, 11th Generation Intel® Core™ I Processors , 2 x DDR4 SO-DIMM, 1 x VGA, 1x HDMI , 7 x USB3.2 (Gen1), 4 x USB2.0, 3 x GbE LAN, 1 x SATA, 2 x RS232, 2 x RS232/422/485, 16bit GPIO, 2 x DI/DO, WDT, SMBus, 2 x M.2 Key B, 1 x Mini PCIe. Onboard TPM. 24V DC.

- **POWER ADAPTER (P/N: 7400120026X00)**
POWER ADAPTER FSP:FSP120-AAAN3(9NA1206609) 120W
24V/5A, W/3PIN PHOENIX CONTACT
- **DC POWER CABLE (P/N: 603POW0391X00)**
POWER CABLE ST:ST-1906022 ATX 2x2P PIT:4.2mm TO
TERMINAL BLOCKS 3P PIT:5.08mm L=230mm
- **SATA POWER CABLE (P/N: 60233PW168X00)**
SATA POWER CABLE BEST HOUSING 4P TO HOUSING 5P
L=250mm
- **SATA CABLE (P/N: 60233AT101X00)**
SATA CABLE ST:MD-6101082 180D (LOCK) TO 180D (LOCK)
CON L=380mm